

AMENDMENTS TO THE TITLE AND ABSTRACT

In The Title:

Please amend the title as follows:

A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND A
METHOD OF MANUFACTURING THE SAME TO PROVIDE IMPROVED
ADHESION BETWEEN BONDING PADS AND BALL PORTIONS OF ELECTRICAL
CONNECTORS

In The Abstract:

Please replace the Abstract with the new Abstract attached hereto as
Appendix A.

ABSTRACT

A method is provided to improve adhesion between bonding pads and ball portions of gold wires to improve reliability of a semiconductor device. About 1 wt.% of Pd is contained in gold wires for connection between electrode pads formed on a wiring substrate and electrode pads (exposed areas of a top layer wiring formed mainly of Al) formed on a semiconductor chip. In bonded portions between the electrode and ball portions of the gold wires, an interdiffusion of Au and Al is suppressed to prevent the formation of Au_4Al after POT (Pressure Cooker Test). Thus, a desired bonding strength is obtained even when the pitch of the electrode pads is smaller than 65 μm and the diameter of the ball portion is smaller than 55 μm or the diameter of the wire portion of each gold wire is not larger than 25 μm .

APPENDIX A